ES1F-ES1J

Fast Rectifiers

Features

- For Surface Mount Applications
- Glass Passivated Junction
- Low Profile Package
- Easy Pick and Place
- Built-in Strain Relief
- Superfast Recovery Times for High Efficiency

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

			Value			
Symbol	Parameter	ES1F	ES1G	ES1H	ES1J	Unit
V _{RRM}	Maximum Repetitive Reverse Voltage	300	400	500	600	V
I _{F(AV)}	Average Rectified Forward Current	1.0			Α	
I _{FSM}	Non-repetitive Peak Forward Surge Current 8.3 ms Single Half-Sine-Wave (JEDEC method)	30			A	
T _J	Junction Temperature		15	50		°C
T _{STG}	Storage Temperature Range	–55 to 150		°C		
P_{D}	Power Dissipation		1.	47		W

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



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SMA (DO-214AC) Color Band Denotes Cathode CASE 403AE

ORDERING INFORMATION

Device	Package	Shipping [†]
ES1F	SMA (Pb-Free)	7500 / Tape & Reel
ES1G	SMA (Pb-Free)	7500 / Tape & Reel
ES1H	SMA (Pb-Free)	7500 / Tape & Reel
ES1J	SMA (Pb-Free)	7500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

THERMAL CHARACTERISTICS

Symbol	Characteristics	Value	Unit
$R_{ heta JA}$	Thermal Resistance, Junction to Ambient (Note 1)	85	°C/W
$R_{ heta JL}$	Thermal Resistance, Junction to Lead (Note 1)	35	°C/W

^{1.} P. C. B mounted on $0.2'' \times 0.2''$ (5 × 5 mm) copper Pad Area.

ELECTRICAL CHARACTERISTICS (T_C = 25°C, unless otherwise noted)

		Value				
Symbol	Characteristics	ES1F	ES1G	ES1H	ES1J	Unit
V_{F}	Maximum Forward Voltage @ I _F = 1.0 A	1.	.3	1.	.7	V
T _{rr}	Maximum Reverse Recovery Time, $I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}, I_{RR} = 0.25 \text{ A}$	35		ns		
I _R	Maximum Reverse Current @ rated V_R $T_A = 25^{\circ}C$ $T_A = 100^{\circ}C$	5.0 100		μΑ		
C _j	Typical Junction Capacitance, V _R = 4.0 V, f = 1.0 MHz	10	0.0	8.	.0	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL PERFORMANCE CHARACTERISTICS

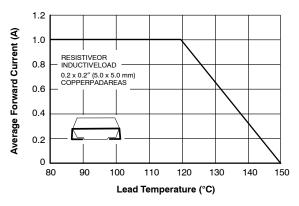


Figure 1. Maximum Forward Current Derating Curve

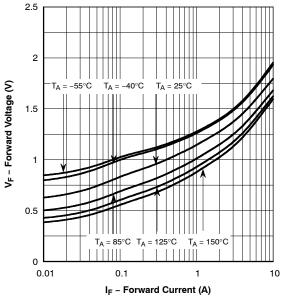


Figure 3. Forward Current vs. Forward Voltage

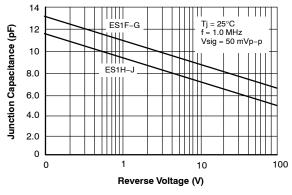


Figure 5. Typical Junction Capacitance

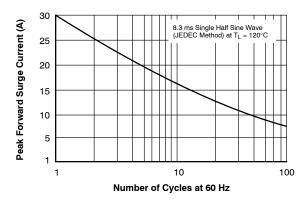


Figure 2. Maximum Non-repetitive Peak Forward Surge Current

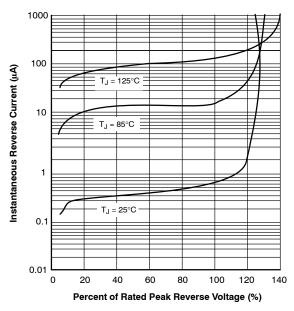
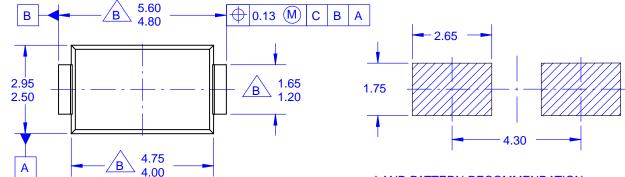


Figure 4. Typical Reverse Characteristics

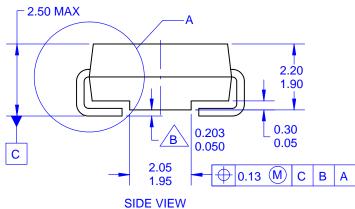
SMA CASE 403AE ISSUE O

DATE 31 AUG 2016



TOP VIEW

LAND PATTERN RECOMMENDATION



NOTES:

- A. EXCEPT WHERE NOTED, CONFORMS ^ TO JEDEC DO214 VARIATION AC.
- B DOES NOT COMPLY JEDEC STANDARD VALUE.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- E. DIMENSIONS AND TOLERANCE AS PER ASME Y14.5–2009.
- E. LAND PATTERN STD. DIOM5025X231M

	8°0°	
R0.15 4X		
GAGE PLANE		
0.45		
8° 0°	1.52	
	DETAIL A SCALE 20 : 1	

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